

Product features

High precision machining technology

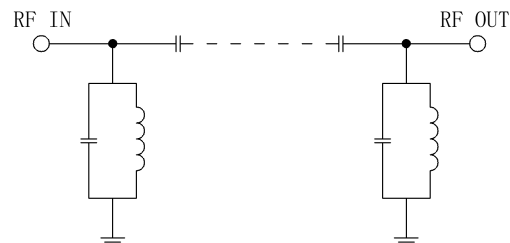
Low temperature drift, high power.

Ceramic substrate, 50 Ω coplanar waveguide

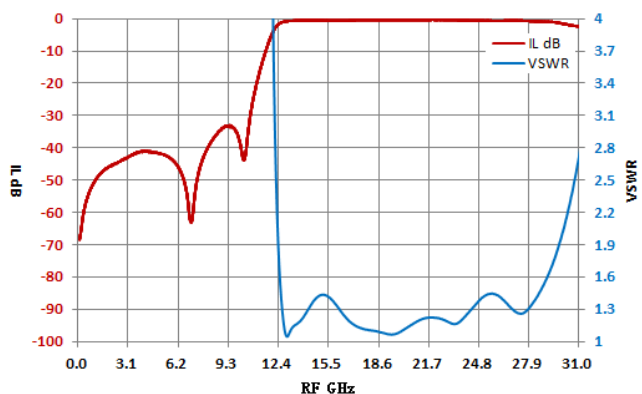
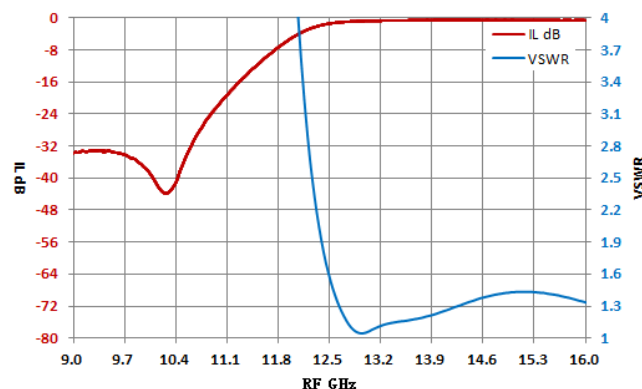
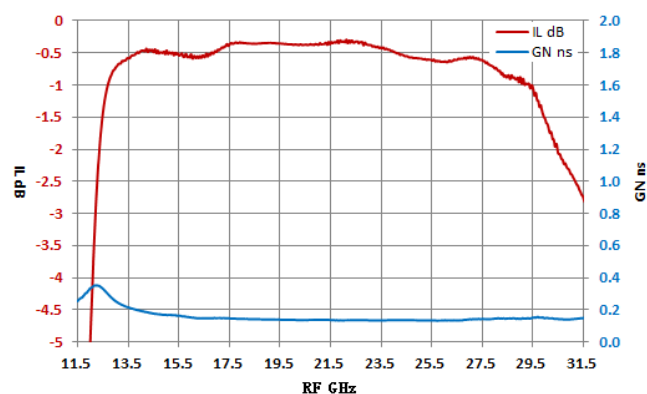
Gold wire bonding



Schematic diagram



Typical test curve



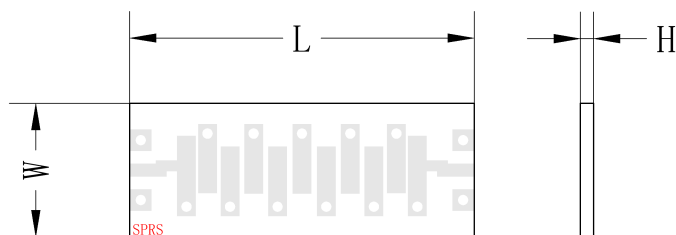
Tech specifications

Items	Parameters	Units
Center Frequency	20.9	GHz
Bandwidth	12.8-29.0	GHz
Passband IL	1.5	dB
Ripple	1.0	dB
VSWR	1.7:1	
Group delay ripple	0.3	ns
Rejection	28@DC-10.3GHz	dBc

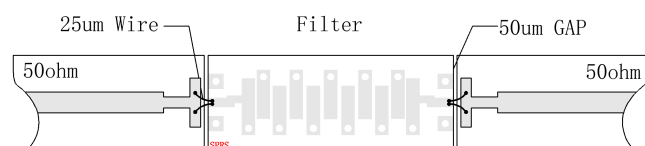
Other requirement (Design assurance)

power	1W CW
Work Temp.	-55~+85°C
Storage Temp.	-55~+125°C
Outline size	L:3.0, W:2.0, h:0.26

Outline drawing: Port centered



Suggested PCB Layout



PCB Rogers5880, h: 0.254mm	PCB Rogers4350B, h: 0.254mm

Note: The specifications and performance data contained in this data sheet are based on tests established by CMW.

Note

1: 0.1mm from the side wall, 2.75mm from the surface to the upper cover.

2: Suggest using conductive adhesive for bonding;

3: The chip should be installed on kovar alloy or molybdenum copper;

4: Suggest using a T-shaped structure for microstrip bonding.